

P-Channel 60-V (D-S) MOSFET

PRODUC	T SUMMARY		
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)	Q _g (Typ)
- 60	0.100 at V _{GS} = - 10 V	- 20	12.5
- 00	0.120 at V _{GS} = - 4.5 V	- 15	12.5

FEATURES

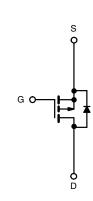
- TrenchFET[®] Power MOSFET
- 100 % UIS Tested

APPLICATIONS

Load Switch







P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_{C} = 25$	5 °C, unless othe	rwise noted		
Parameter		Symbol	Limit	Unit
Gate-Source Voltage		V _{GS}	± 20	V
Continuous Drain Current ($T_1 = 175 \ ^{\circ}C$)	T _C = 25 °C	1-	- 20	
Continuous Drain Current (1) = 175 C)	T _C = 100 °C	I _D	- 12	
Pulsed Drain Current	I _{DM}	- 60	А	
Continuing Source Current (Diode Conduction)	۱ _S	- 12		
Avalanche Current	I _{AS}	- 12		
ngle Pulse Avalanche Energy L = 0.1 mH		E _{AS}	7.2	mJ
Maximum Dawar Dissinction	T _C = 25 °C	Р	30 ^a	14/
Maximum Power Dissipation	T _A = 25 °C	P _D	2 ^b	W
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
hunding to Ambient	$t \le 10 \text{ sec}$	R _{thJA}	20	25			
Junction-to-Ambient ^D	Steady State		62	75	°C/W		
Junction-to-Case		R _{thJC}	5	6			

Notes:

a. See SOA curve for voltage derating.

b. Surface Mounted on 1" x 1" FR-4 boad.

SPECIFICATIONS $T_J = 25$	°C, unless	otherwise noted					
Parameter	Symbol	Test Conditions	Min	Typ ^a	Мах	Unit	
Static		· · · ·					
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 V, I_D = -250 \mu A$	- 60			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1.0	- 2.0	- 3.0	v	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1		
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} = - 60 V, V_{GS} = 0 V, T_{J} = 125 °C			- 50	μΑ	
		V_{DS} = - 60 V, V_{GS} = 0 V, T_{J} = 175 °C			- 150		
On-State Drain Current ^b	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 10			А	
		V _{GS} = - 10 V, I _D = - 5 A		0.100		Ω	
	r	V_{GS} = - 10 V, I_D = - 5 A, T_J = 125 °C		0.150			
Drain-Source On-State Resistance ^b	r _{DS(on)}	V_{GS} = - 10 V, I_D = - 5 A, T_J = 175 °C		0.200			
		V _{GS} = - 4.5 V, I _D = - 2 A		0.120			
Forward Transconductance ^b	9 _{fs}	V _{DS} = - 15 V, I _D = - 5 A		8		S	
Dynamic	+	•		•			
Input Capacitance	C _{iss}			550			
Output Capacitance	C _{oss}	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$		95		pF	
Reverse Transfer Capacitance	C _{rss}			60		1	
Total Gate Charge	Qg			12.5	19	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = -30$ V, $V_{GS} = -10$ V, $I_{D} = -8.4$ A		2.3			
Gate-Drain Charge	Q _{gd}			3.2		1	
Gate Resistance	Rg	f = 1 MHz		8.0		Ω	
Turn-On Delay Time ^c	t _{d(on)}			5	10	ns	
Rise Time ^c	t _r	V_{DD} = - 30 V, R_L = 3.57 Ω		14	25		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong$ - 8.4 A, V_{GEN} = - 10 V, R_G = 2.5 Ω		15	25		
Fall Time ^c	t _f]		7	12		
Source-Drain Diode Ratings and Cha	racteristics	(T _C = 25 °C) ^b					
Pulsed Current	I _{SM}				- 20	А	
Forward Voltage ^b	V _{SD}	I _F = - 2 A, V _{GS} = 0 V		- 0.9	- 1.3	V	
Reverse Recovery Time	t _{rr}	I _F = - 8 A, di/dt = 100 A/μs		50	80	ns	
Reverse Recovery Time	Q _{rr}	$r_{\rm F} = -6 {\rm A}, {\rm d} / {\rm d} t = 100 {\rm A} / {\rm \mu} {\rm S}$		80	120	nC	

Notes:

a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

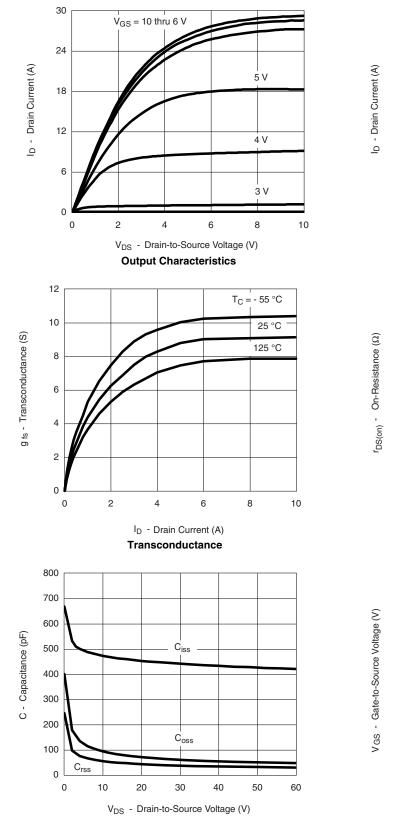
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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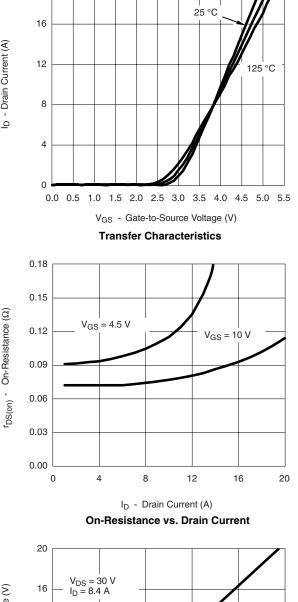


T_C = - 55 °C

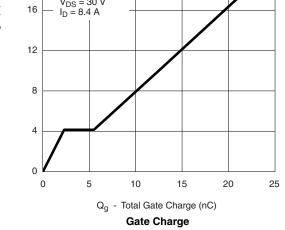


Capacitance

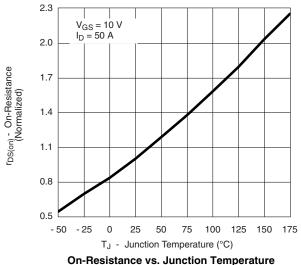
TYPICAL CHARACTERISTICS 25 °C unless noted

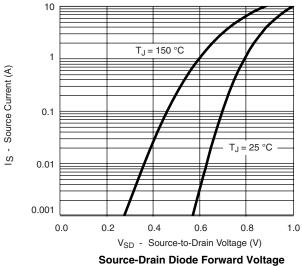


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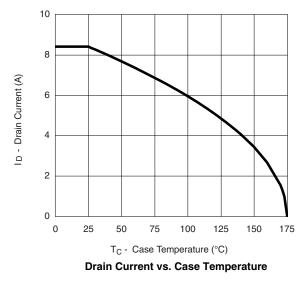


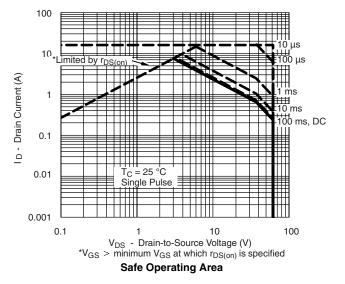


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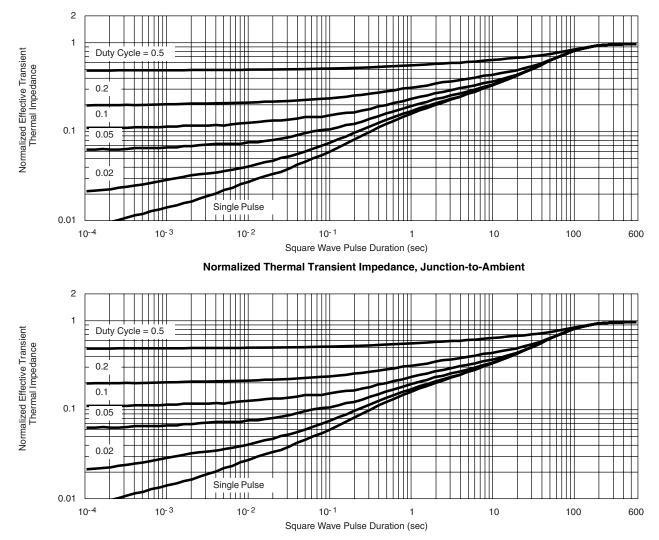
THERMAL RATINGS







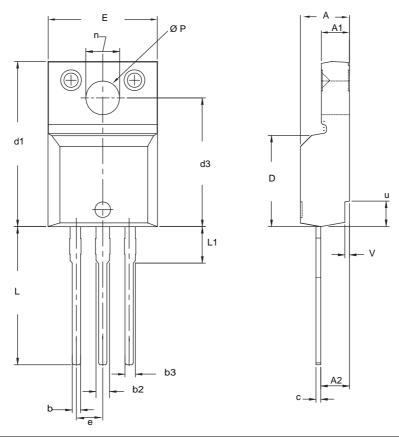
THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



TO-220 FULLPAK



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
А	4.570	4.830	0.180	0.190
A1	2.570	2.830	0.101	0.111
A2	2.510	2.850	0.099	0.112
b	0.622	0.890	0.024	0.035
b2	1.229	1.400	0.048	0.055
b3	1.229	1.400	0.048	0.055
С	0.440	0.629	0.017	0.025
D	8.650	9.800	0.341	0.386
d1	15.88	16.120	0.622	0.635
d3	12.300	12.920	0.484	0.509
E	10.360	10.630	0.408	0.419
е	2.54	BSC	0.100) BSC
L	13.200	13.730	0.520	0.541
L1	3.100	3.500	0.122	0.138
n	6.050	6.150	0.238	0.242
ØP	3.050	3.450	0.120	0.136
u	2.400	2.500	0.094	0.098
V	0.400	0.500	0.016	0.020

DWG: 5972

Notes

1. To be used only for process drawing. 2. These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads. 3. All critical dimensions should C meet $C_{pk} > 1.33$. 4. All dimensions include burrs and plating thickness. 5. No chipping or package damage.



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